

MSKSEMI

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT

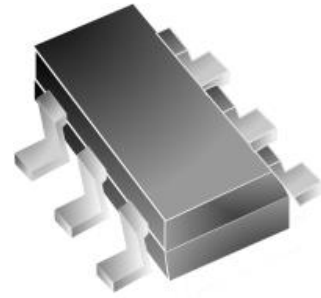


PLED

Product data sheet

FEATURES:

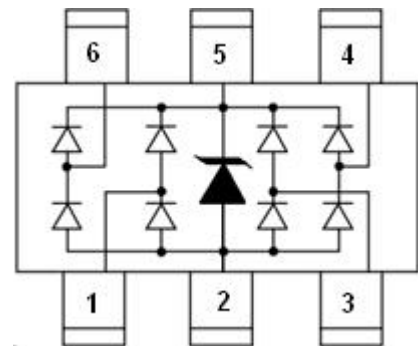
- 100 watts peak pulse power per line ($t_P=8/20\mu s$)
- Protects four I/O lines
- Low clamping voltage
- Low operating voltage
- Low capacitance
- RoHS compliant



SOT-23-6

MAIN APPLICATIONS

- USB 2.0&3.0 power and data line protection
- Digital video interface (DVI)
- Notebook computers
- Video graphics cards
- Monitors and flat panel displays
- 10/100/1000 ethernet
- SIM ports
- ATM interfaces



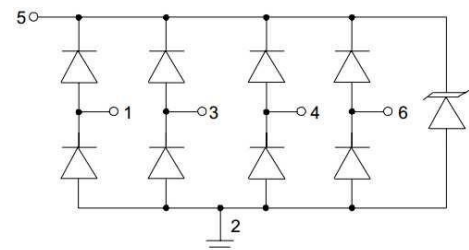
PIN Configuration

PROTECTION SOLUTION TO MEET

- IEC61000-4-2 (ESD) $\pm 20kV$ (air), $\pm 20kV$ (contact)
- IEC61000-4-4 (EFT) 40A (5/50ns)
- IEC61000-4-5 (Lightning) 5A (8/20 μs)

MECHANICAL CHARACTERISTICS

- Molding compound flammability rating: UL 94V-0
- Quantity per reel: 3, 000pcs
- Lead finish: lead free



Circuit Diagram

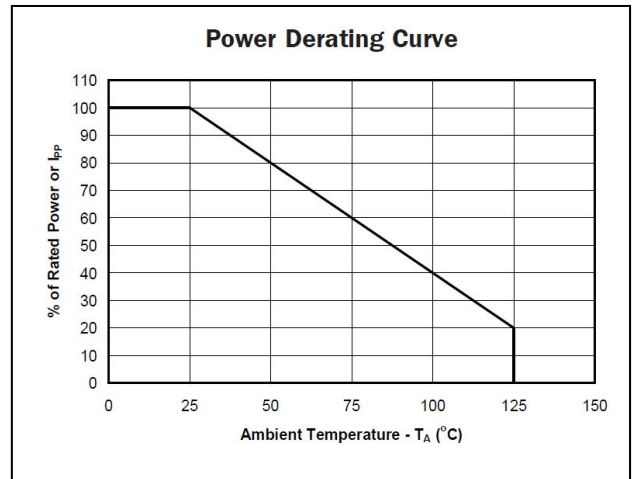
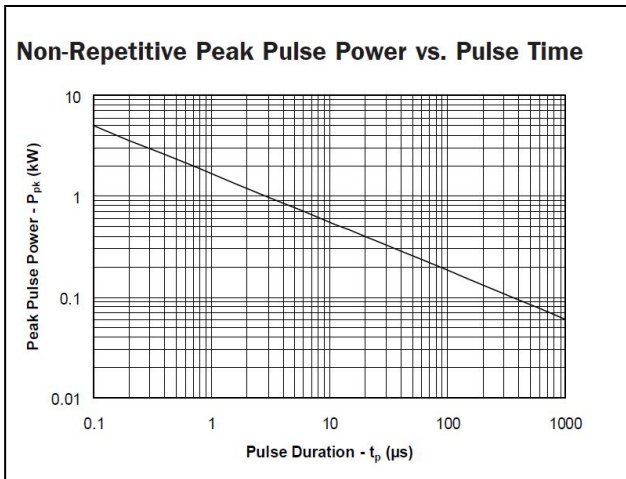
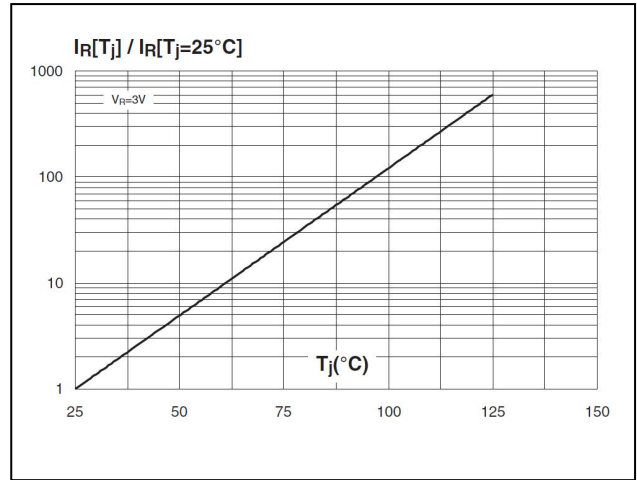
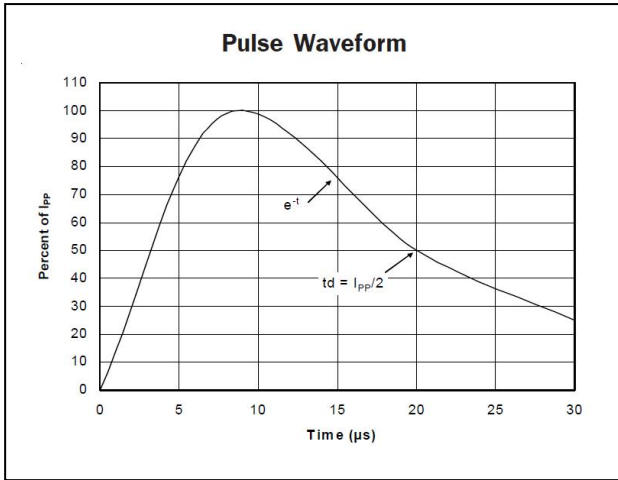
ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}\text{C}$, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20 μs waveform	P_{PP}	100	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 20 +/-20	kV
Lead soldering temperature	T_L	260 (10 sec.)	$^{\circ}\text{C}$
Operating junction temperature range	T_J	-55 to +125	$^{\circ}\text{C}$
Storage temperature range	T_{STG}	-55 to +150	$^{\circ}\text{C}$

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$)

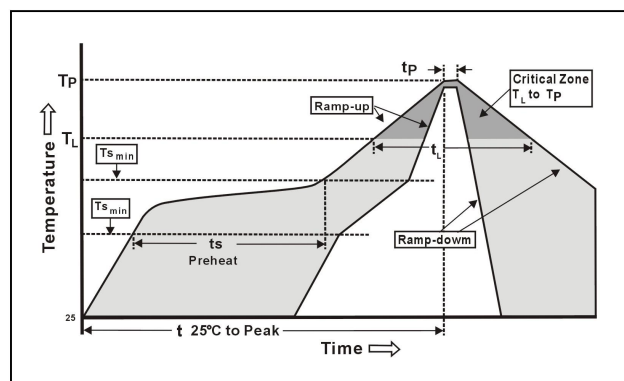
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				5.0	V
Reverse breakdown voltage	V_{BR}	$I_T=1\text{mA}$	6.0			V
Reverse leakage current	I_R	$V_{RWM}=5\text{V}$			1	μA
Forward voltage	V_F	$I_T=10\text{mA}$		0.8	1.0	V
Clamping voltage (I/O pin to Ground)	V_C	$I_{PP}=1\text{A}$, $t_P=8/20\mu\text{s}$		9.5	11	V
	V_C	$I_{PP}=5\text{A}$, $t_P=8/20\mu\text{s}$		12.5	15	
Junction capacitance	C_J	$V_{RWM}=0\text{V}$, $f=1\text{MHz}$ Any I/O pin to Ground		0.65	0.8	pF
		$V_{RWM}=0\text{V}$, $f=1\text{MHz}$ Between I/O pins		0.3	0.5	

Typical Characteristics@ Ta=25°C unless otherwise specified

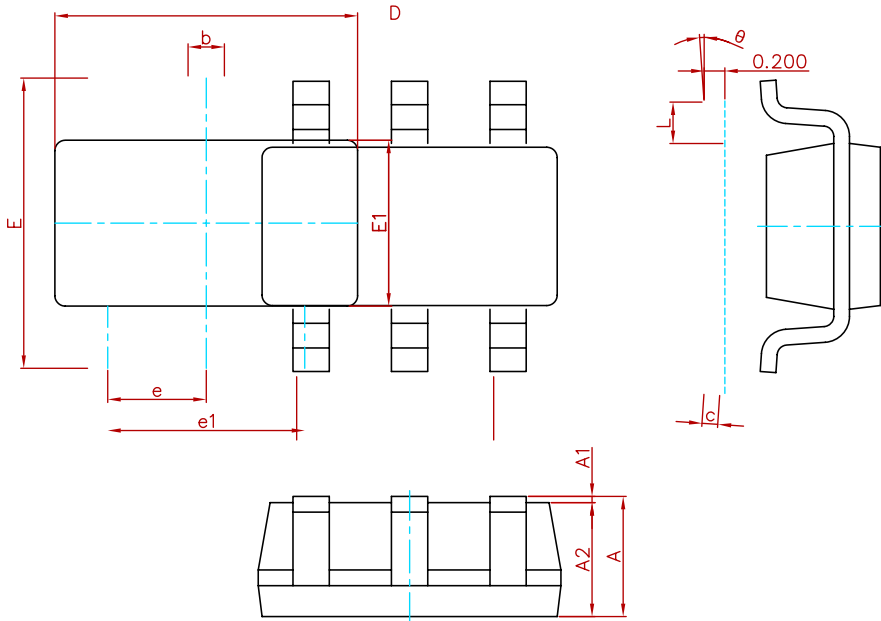


Soldering Parameters

Reflow Condition		Fb – Free assembly
Pre Heat	- Temperature Min ($T_{s(\text{Min})}$)	150°C
	- Temperature Max ($T_{s(\text{Max})}$)	200°C
	- Time (Min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second Max
$T_{s(\text{Max})}$ to T_L - Ramp-up Rate		3°C/second Max
Reflow	- Temperature (T_L) (Liquidus)	217°C
	- Temperature (t_L)	60 – 150 seconds
Peak Temperature (T_p)		250 ^{+0/-5} °C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second Max
Time 25°C to peak Temperature (T_p)		8 minutes Max.
Do not exceed		260°C

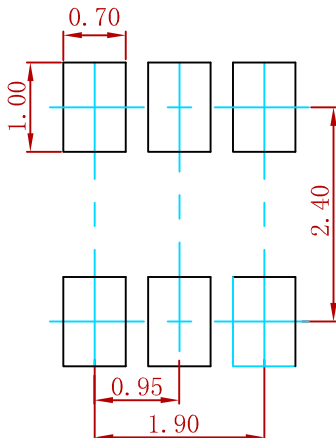


PACKAGE MECHANICAL DATA



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E1	1.500	1.700	0.059	0.067
E	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

Suggested Pad Layout



- Note:
1. Controlling dimension: in millimeters.
 2. General tolerance: ± 0.05mm.
 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
MSRV05-4	SOT-23-6	3000

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